Efficient Sensitivity-Based Capacitance Modeling for Systematic and Random Geometric Variations

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Outline

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 - Systematic & random variations
 - Modeling method (panel sensitivity)
- Modeling for systematic variations
- Modeling for random variations
 - Panel sensitivity based statistical modeling method
 - Experiments and results
 - Case study: 8-bit binary-scaled charge-redistribution DAC
- Modeling for both variations
 - Diagram
 - Experiment and result
- Conclusion



Process Variability

- Systematic Variation
 - Lithography, Etching, CMP
 - Layout dependent
- Random Variation





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Process Variability

- Systematic Variation
 - Lithography, Etching, CMP
 - Layout dependent
- Random Variation
 - Line-edge roughness
 - Spatial correlation





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Process Variability





Modeling Method

- BEM-based capacitance extraction
 - Partial short-circuit capacitances $\overline{\mathbf{C}}$
 - Nominal capacitance C_{0} : sum of associated partial short-circuit capacitances \overline{C}





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Modeling Method

Panel sensitivity



- ρ_k : a small displacement of a panel k
- \mathcal{E} : material permittivity around panel k
- A_k : the area of panel k
- $\overline{C}_{k,a}$: an entry in the partial short-circuit capacitance matrix
- $\sum_{a \in N_i} \overline{\overline{C}}_{k,a}$: capacitance between a panel *k* and a node *i*



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Modeling Method

Panel sensitivity

have been produced in calculation of the nominal C₀ using BEM

$$S_{k,ij} = \frac{\partial C_{ij}}{\partial \rho_k} = -\frac{1}{\epsilon A_k} \sum_{a \in N_i} \sum_{b \in N_j} \overline{C}_{k,a} \overline{C}_{k,b}$$

[Bi-CICC-2009]

- no extra costly computation
- partial capacitances

(data for standard capacitance extraction)

- BEM
- FAST!



Modeling for Systematic Variation

• Linear / sensitivity model

$$\mathbf{C} = \mathbf{C}_{\mathbf{0}} + \sum_{i} \frac{\partial \mathbf{C}}{\partial \mathbf{p}_{i}} \cdot \Delta \mathbf{p}_{i}$$

$$\frac{\partial \mathbf{C}_{ij}}{\partial \mathbf{p}} = \sum_{\mathbf{k} \in \mathbf{s}_{p}} \mathbf{S}_{\mathbf{k},ij}$$

- s_p : the set of panels incident to the geometric parameter p



Modeling for Systematic Variation

• Linear / sensitivity model

$$\mathbf{C} = \mathbf{C}_{\mathbf{0}} + \sum_{i} \frac{\partial \mathbf{C}}{\partial \mathbf{p}_{i}} \cdot \Delta \mathbf{p}_{i}$$

$$\frac{\partial \mathbf{C}_{ij}}{\partial \mathbf{p}} = \sum_{\mathbf{k} \in \mathbf{s}_{p}} \mathbf{S}_{\mathbf{k},ij}$$

- s_p : the set of panels incident to the geometric parameter p
- Variance of capacitance due to the dimensional variation:

$$\operatorname{var}(\mathbf{C}_{j})_{sys} = (\sum_{k \in s_p} S_{k,ij})^2 \sigma_p^2$$

[Bi-CICC-2009]

- $\boldsymbol{\sigma}_p$: standard deviation of parameter p



Modeling for Random Variations

 Modeling the effects of Line-Edge Roughness (LER) on capacitances





Statistical Model of Capacitances

Capacitance Modeling

$$\Delta C = \sum_{l=1}^{L} \sum_{i=1}^{n_l} S_i \rho_i$$

- $\Delta C\,$: capacitance variation induced by the LER
- ρ : a sequence of random variables (panel displacements)
- S_i : panel sensitivity associated with panel displacement ρ_i
- \mathbf{n}_1 : the number of deviation panels for rough line l
- \mathbf{L} : the number of rough lines



Statistical Model of Capacitances

Capacitance Modeling

$$\Delta C = \sum_{l=1}^{L} \sum_{i=1}^{n_l} S_i \rho_i$$

- Variance of ΔC

$$\sigma_{\Delta C}^{2} = var(\sum_{l=1}^{L}\sum_{i=1}^{n_{l}}S_{i}\rho_{i})$$

Some P_i s are NOT independent !!



Statistical Model of Capacitances

Capacitance Modeling

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- Variance of ΔC

$$\sigma_{\Delta C}^{2} = var\left(\sum_{l=1}^{L}\sum_{i=1}^{n_{l}}S_{i}\rho_{i}\right)$$
$$\sigma_{\Delta C}^{2} = \sum_{l=1}^{L}\left[\sum_{i=1}^{n_{l}}s_{i}^{2}var(\rho_{i}) + 2\sum_{i,j:i < j}s_{i}s_{j}cov(\rho_{i},\rho_{j})\right]$$



Random Variation

$$\sigma_{\Delta C}^{2} = \sum_{l=1}^{L} \left[\sum_{i=1}^{n_{1}} s_{i}^{2} \underline{var(\rho_{i})} + 2 \sum_{i,j:i < j} s_{i} s_{j} cov(\rho_{i},\rho_{j}) \right]$$

$$\operatorname{var}(\rho_i) = \sigma_{LER}^2$$





Random Variation

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Any correlation function!





Random Variation

$$\sigma_{\Delta C}^{2} = \sum_{l=1}^{L} \left[\sum_{i=1}^{n_{l}} s_{i}^{2} \underline{var(\rho_{i})} + 2 \sum_{i,j:i < j} s_{i} \underline{s_{j}cov(\rho_{i},\rho_{j})} \right]$$

 $\operatorname{var}(\rho_i) = \sigma_{LER}^2$

• Gaussian correlation function:

$$\operatorname{cov}(\rho_{i},\rho_{j}) = \sigma_{LER}^{2} \exp(-\frac{|r_{i,y} - r_{j,y}|^{2}}{\eta_{LER}^{2}})$$

 $\mathcal{R}_{i,y}$ is the y-coordinate of the position associated with \mathcal{P}_i

 η_{LER} is the correlation length in y-direction

Two characterization parameters





Experiment - I

 $\sigma_{LER} = 3.5 nm$ $\eta_{LER} = 16 nm$

- Measurement data from IMEC [Stucchi - 2007]
- Relative std. deviation: $\frac{\sigma_c}{C}$
- Monte-Carlo simulation
 - 1000 samples





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	$\sigma_{_C} / C$	Error	CPU Time
MC simulation	0.681%	-	48653''
Proposed model	0.603%	11.5%	50''



Experiment - II

Using the proposed model, one can easily study:

- 1. The relationship between $\frac{\sigma_c}{C}$ and the conductor length;
- 2. The impact of parameters σ_{LER} and η_{LER} on $\frac{\sigma_{C}}{C}$.



- Same structure as Experiment-I
- 5 examples of mismatches
- Combination of various $\sigma_{\scriptscriptstyle L\!E\!R}$ and $\eta_{\scriptscriptstyle L\!E\!R}$
- Application:
 - High accuracy vs. low power consumption



Experiment - II

Using the proposed model, one can easily study:

- 1. The relationship between $\frac{\sigma_c}{C}$ and the conductor length;
- 2. The impact of parameters $\sigma_{\scriptscriptstyle LER}$ and $\eta_{\scriptscriptstyle LER}$ on $\frac{\sigma_{\scriptscriptstyle C}}{C}$.



- Two sweeping parameters
- Proposed method: an hour
- MC approach: 43 days

ÍUDelft



Experiment - II

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- 1. The relationship between $\frac{\sigma_c}{C}$ and the conductor length;
- 2. The impact of parameters $\sigma_{\scriptscriptstyle LER}$ and $\eta_{\scriptscriptstyle LER}$ on $\frac{\sigma_{\scriptscriptstyle C}}{C}$.



The proposed modeling method provides a fast and practical tool for circuit designers to estimate mismatches and optimize dimensions of critical structures accordingly.



A Case Study

- Novel passive devices with high-precision structures
- 8-bit charge-redistribution DAC
 - 255 identical unit capacitors
 - Min. value of a unit capacitor for high power efficiency (0.5fF)
 - Main consideration: mismatch of capacitors $(\frac{\sigma_{C_0}}{C})$





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• Design requirement: mismatch of the unit capacitor < 1%



A Case Study

- <u>Design</u> requires:
 - mismatch of the unit capacitor < 1%
- Simulation shows:
- The mismatch of the unit capacitor caused by the LER is around 0.25%;
- <u>Measurement</u> indicates:
- A random mismatch of the unit capacitor being **better than 0.6%**;
- <u>Simulation</u> and <u>measurement</u> together conclude:
- Simulation results are very reasonable;
- The structure can be used for more accurate designs: e.g. 10-bit DAC (designer's plan!);

Design tool enables a new design, based on proper modeling but NOT guessing



Sensitivity Based Modeling for Both Systematic and Random Variations

Design For Manufacturing





Experiment - III

- Two parallel conductors
- width/space = $2\mu m/2\mu m$; thickness = $2\mu m$; length = $8\mu m$
- LER on four edges of two conductors:

 $\sigma_{LER} = 0.03 \,\mu m, \quad \eta_{LER} = 2.00 \,\mu m$ $\sigma_{LER} = 0.04 \,\mu m, \quad \eta_{LER} = 2.88 \,\mu m$

- Systematic variation of the two conductors: $\sigma_{sys} = 0.03 \,\mu m$, $\sigma_{sys} = 0.04 \,\mu m$
- Parameters are chosen based on pure assumption



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- Systematic variation of the two conductors: $\sigma_{sys} = 0.03 \,\mu m$, $\sigma_{sys} = 0.04 \,\mu m$
- Parameters are chosen based on pure assumption
- 3 Monte Carlo simulations with 1000 samples each
 - Systematic variation
 - Random variation
 - Superposition of the above two



Experiment - III

	MC simulation	Proposed method
$\sigma_{\scriptscriptstyle C_{\scriptscriptstyle sys}}$ / C	2.22%	2.05% (7.72% error)
$\sigma_{_{C_{\scriptscriptstyle L\!E\!R}}}$ / C	0.21%	0.24% (14.23% error)
$\sigma_{_{C_{sNr}}}$ / C	2.22%	2.06% (7.18% error)
CPU Time	38h52′	58″

- The systematic variation is the dominant one
- Some designs are sensitive to both variations and some (e.g. 8-bit DAC) are only vulnerable to random variations
- Being able to apply the appropriate modeling techniques is essential

Extremely high efficiency + good enough accuracy = a fast and convenient tool for DFM !



Conclusion

- Sensitivity based method for statistical property of capacitances due to both systematic and random variations
- Modeling method for the effect of LER on capacitance
 - Simulations & measurement on chips
 - Good enough accuracy & high efficiency
 - Useful and convenient tool for mismatch estimation & circuit optimization
- Overall picture of the sensitivity based method for both variations
 - Extension of BEM LPE tools
 - Serving DFM!

